ASSOCIATION CONNECTING
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IPC/JPCA-2315

Design Guide for High Density Interconnects (HDI) and Microvias

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A standard developed by IPC and JPCA

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- Minimize time to market
- Contain simple (simplified) language
- Just include spec information
- Focus on end product performance
- Include a feedback system on use and problems for future improvement

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- Increase time-to-market
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Developed by the High Density Interconnect (HDI) Design Subcommittee (D-41) of the High Density Interconnect (HDI) Committee (D-40) of IPC and the Build-Up PWB Committee of the Japan Printed Circuit Association (JPCA)

Users of this standard are encouraged to participate in the development of future revisions.

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Acknowledgment

Any Standard involving a complex technology draws material from a vast number of sources. While the principal members of the High Density Interconnect (HDI) Design Subcommittee (D-41) of the High Density Interconnect (HDI) Committee (D-40) and the JPCA Build-Up PWB Committee are shown below, it is not possible to include all of those who assisted in the evolution of this standard. To each of them, the members of the IPC and JPCA extend their gratitude.

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